

Title (en)

ELECTRIC HEATING DEVICE, COMPONENT AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

ELEKTRISCHE HEIZVORRICHTUNG, BAUELEMENT SOWIE VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

DISPOSITIF DE CHAUFFAGE ÉLECTRIQUE, COMPOSANT ET LEUR PROCÉDÉ DE FABRICATION

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2013156162A2] The invention relates to an electric heating device (20) having at least one first electrically conductive component (21), at least one heating layer (22) and at least one second electrically conductive component (23). According to the invention, the first electrically conductive component (21) and/or the second electrically conductive component (23) are produced by means of a thermal injection molding process and/or arranged on the heating layer (22). Alternatively or additionally, according to the invention the electrically conductive components (21, 23) and the heating layer (22) are placed in relation to one another such that a current flow perpendicular to the plane of the heating layer (20) and/or in the direction of the plane of the heating layer (20) is or can be realized. In order to produce a component (10), such a heating device (20) can preferably be arranged on a substrate element (11). Furthermore, a suitable production process is described.

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- EP 2714516 A2 20140409 - EADS DEUTSCHLAND GMBH [DE]
- WO 2012159608 A2 20121129 - EADS DEUTSCHLAND GMBH [DE], et al

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